

TI Demonstrates their DualCool Packaging Technology at APEC 2010

Jeff Sherman of TI demonstrated their latest packaging tech - DualCool, which incorporates extra heat-transfer structures in a power MOSFET to improve performance.

For more information visit TI at www.ti.com [1].

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<http://www.ecnmag.com/videos/2010/03/ti-demonstrates-their-dualcool-packaging-technology-apec-2010>

Links:

[1] <http://www.ti.com>